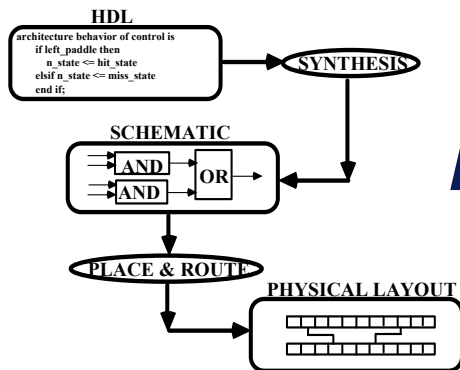


DESIGNING FPGAS & ASICS

Testing ASICs

Prof. Don Bouldin, Ph.D.



Electrical & Computer Engineering

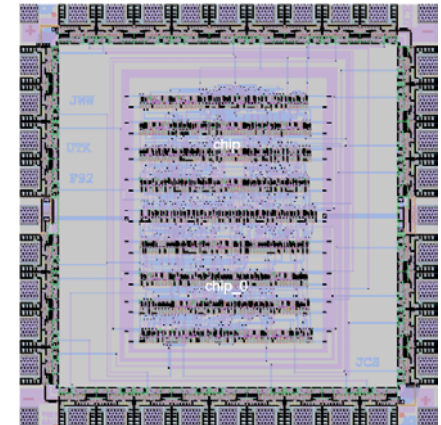
University of Tennessee

TEL: (865)-974-5444

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dbouldin@tennessee.edu

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COURSE OUTLINE

- **Overview of FPGAs and ASICs**
- **Using Synthesis**
- **HDL Examples**
- **Simulation and Testing**
- **Physical Place and Route**
- **Testing ASICs**
- **Component Reuse**

TESTING ASICS

- **Functional Tests**
- **Manufacturing Tests**
- **Fault Coverage**
- **Test Pattern Generation**
- **Internal Scan**
- **Boundary Scan**
- **Built-In Self-Test**

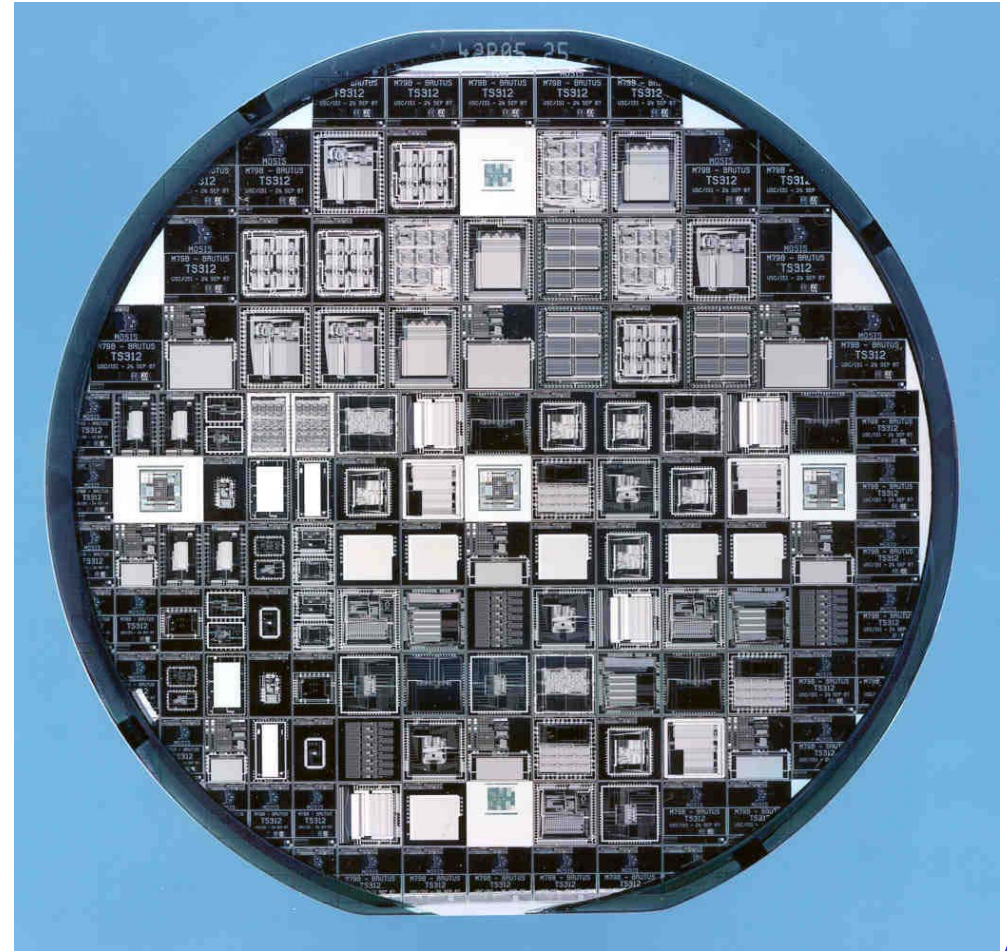
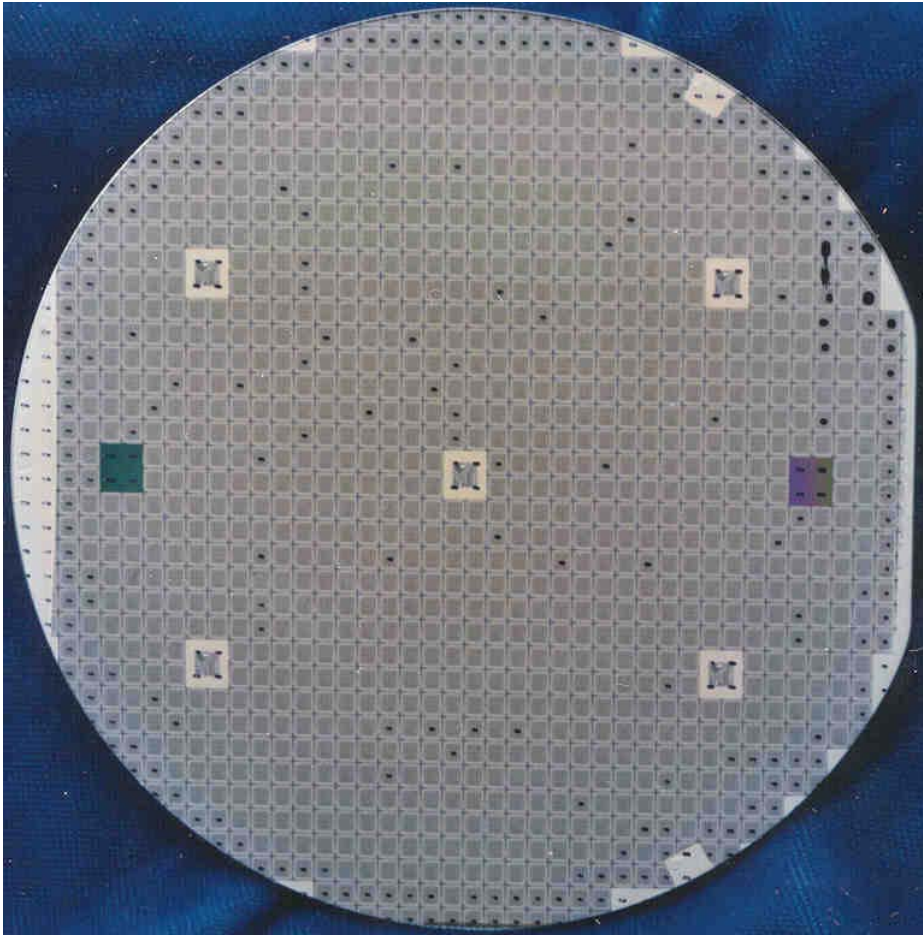
FUNCTIONAL TEST STIMULI

- **Functional test stimuli validate that the circuit exhibits the required behavior at the desired speed.**
- **It is too time-consuming to develop and to apply an exhaustive set of functional stimuli so usually the designer tests only favorite cases and expected trouble spots like overflow, etc.**
- **CAD tools to assist in this process generally take equations and generate 1's and 0's.**

MANUFACTURING TEST STIMULI ARE NECESSARY BUT COSTLY

- **Manufacturing has far less than 100% yield so each part must be tested to determine whether the circuit you desired was actually manufactured.**
- **First, known test structures are probed on the wafer to determine its acceptance.**
- **Then, each die on the wafer is probed and tested at d.c.**
- **Packaged parts are tested individually by the vendor at low speed (usually 1 MHz).**
- **The designer may then screen parts individually at full speed and under various environmental conditions.**

SHARING MULTI-PROJECT MASKS AND WAFERS SAVES MONEY



MOSIS

MANUFACTURING TEST STIMULI AND FAULT COVERAGE

- Manufacturing test stimuli should provide sufficient coverage to achieve the desired quality.
- The more demanding the coverage, the fewer defective parts that will be shipped.
- Fault grading can be applied at the logic-level or at the MOS switch-level. Vendors encourage toggling of all logic nodes from 0 to 1 and 1 to 0 whether used or not.
- A minimum set of stimuli that can detect (not locate) faults is used for screening production parts to minimize time on the tester and its per-pin memory requirements.

DEFECTIVE PARTS AS A FUNCTION OF FAULT COVERAGE PERCENTAGE

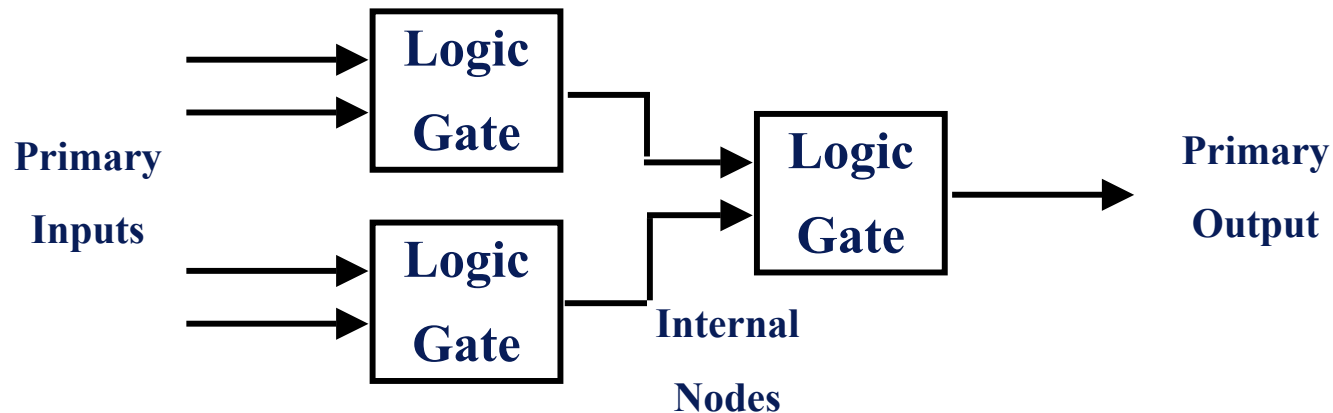
<u>Defective Parts</u>	<u>Fault Coverage</u>
227	50.00%
133	90.00%
90	99.00%
3	99.99%

Out of 10,000 Parts

Table 14.24, Page 795
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GENERATING TEST STIMULI FOR LOGIC FAULT COVERAGE

- Stimuli must be applied to primary inputs and cause the internal nodes to toggle. Responses must be observable from the primary outputs.
- Manufacturing test stimuli are generated before fabrication since the circuit can still be modified to enhance controllability and observability. This is called "design for testability".

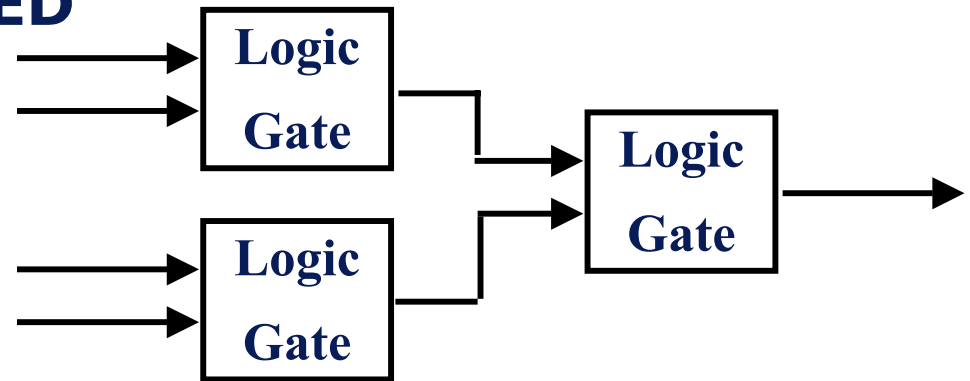


FAULT COVERAGE IS BASED ON THE STUCK-AT MODEL

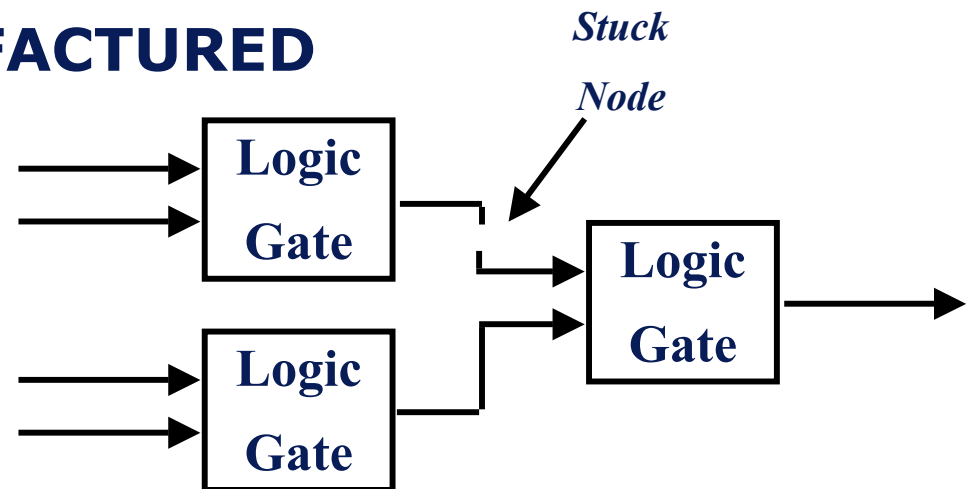
STUCK-AT MODEL

- A node may be **GOOD**, **Stuck-at-0** or **Stuck-at-1**.
- Only one node is considered to be at fault at any one time.

DESIGNED



MANUFACTURED



DETECTION OF STUCK-AT FAULTS

To detect whether F1 at the output of U2 is s-a-1, apply an input of C = 0, B = 1 and A = 1.

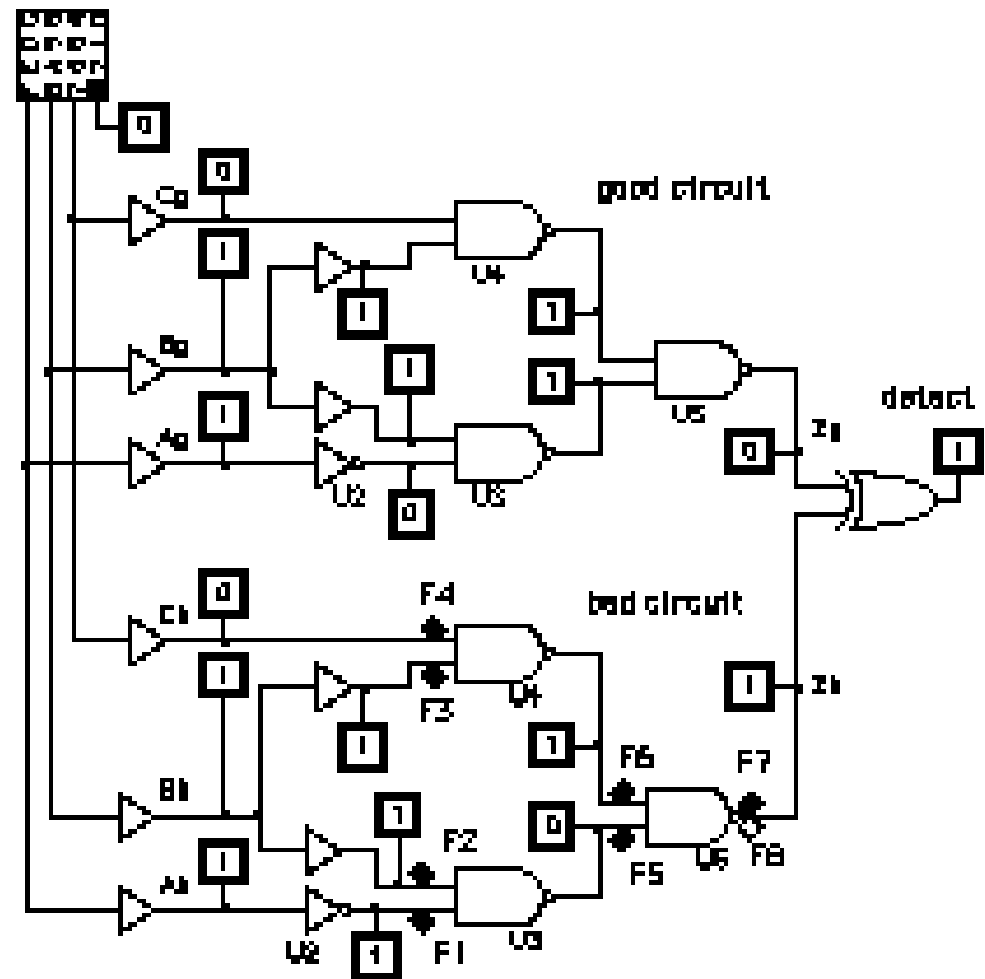
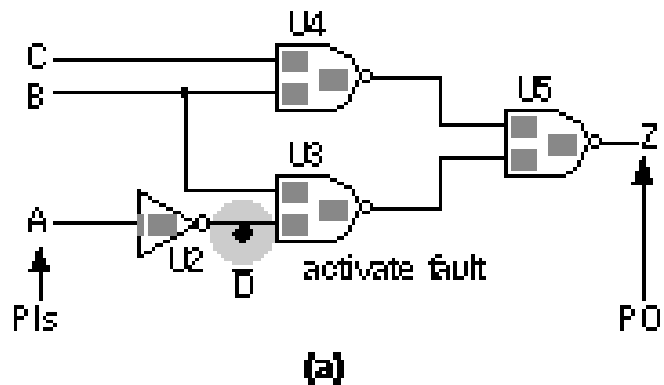


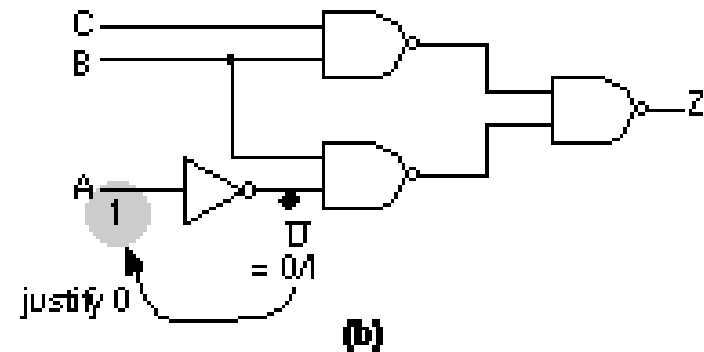
Fig. 14.16, Page 752
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JUSTIFICATION AND PROPAGATION FOR FAULT DETECTION

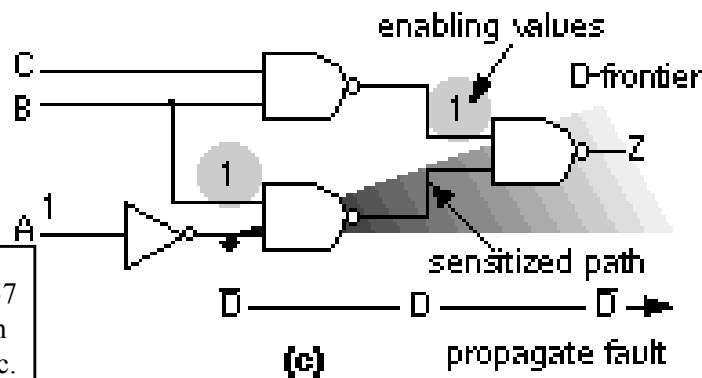
1. Choose a fault



2. Work backward



3. (N)AND gates to 1, (N)OR gates to 0



4. Work backward

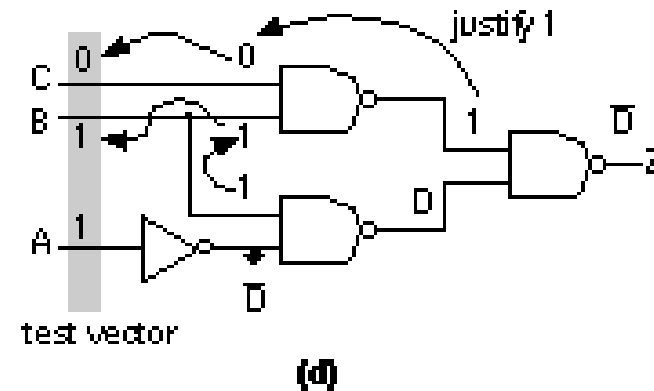
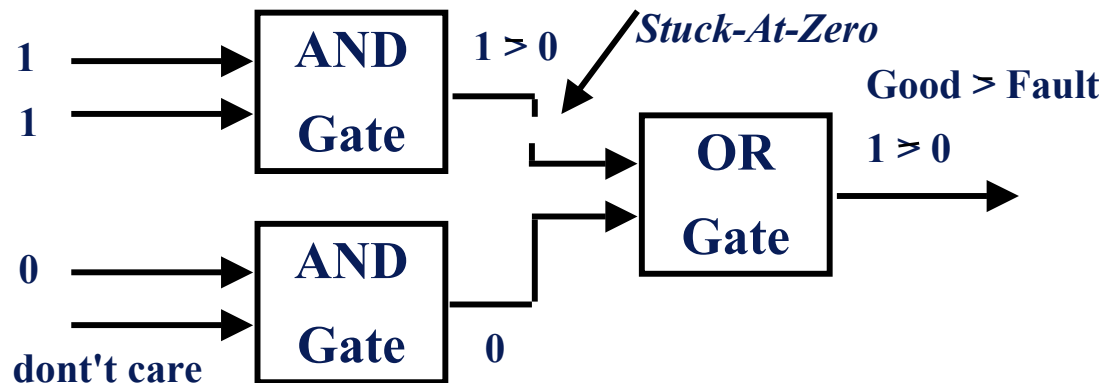


Fig. 14.18, Page 757
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GENERATION OF TEST STIMULI FOR STUCK-AT FAULTS

- **FUNCTIONAL**--generated as a byproduct of verifying the intended operation.
- **EXHAUSTIVE**--too time-consuming for large, practical circuits but okay for small ones. Can use a counter to generate all possible 1's and 0's on the fly.
- **RANDOM**--easily generated on the fly using a linear feedback shift register.
- **DETERMINISTIC**--can be guaranteed to be generated if a test exists. However, this process may require substantial computing resources. Automatic Test Pattern Generator (ATPG) programs like Lasar, Podem and Fan are based on the D-algorithm.



RANDOM PATTERN GENERATION

A Linear Feedback Shift Register (LFSR) can produce a Pseudo-Random Binary Sequence (PBRs).

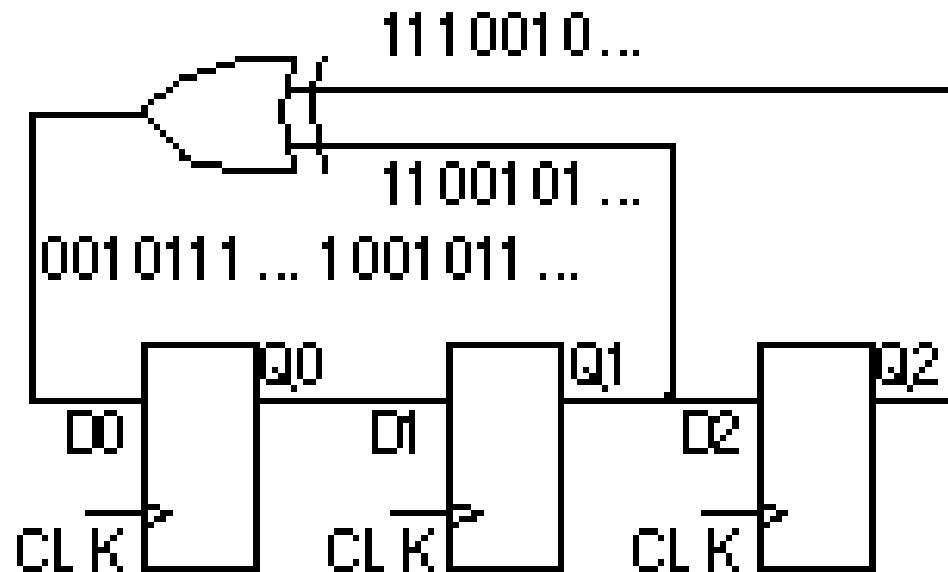
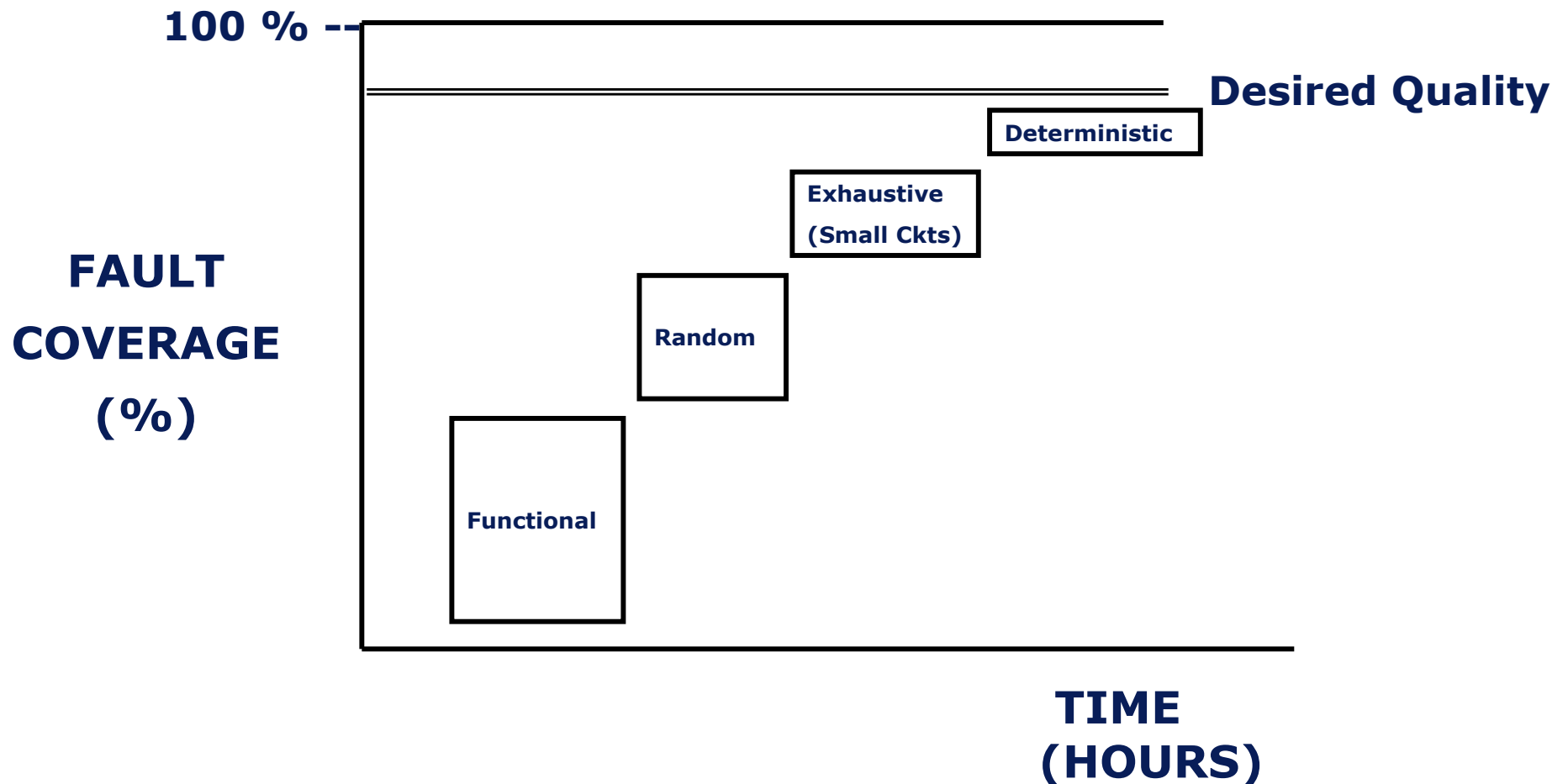


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STRATEGY FOR GENERATING TEST STIMULI



DETERMINISTIC ALGORITHM FOR DETECTING FAULTS

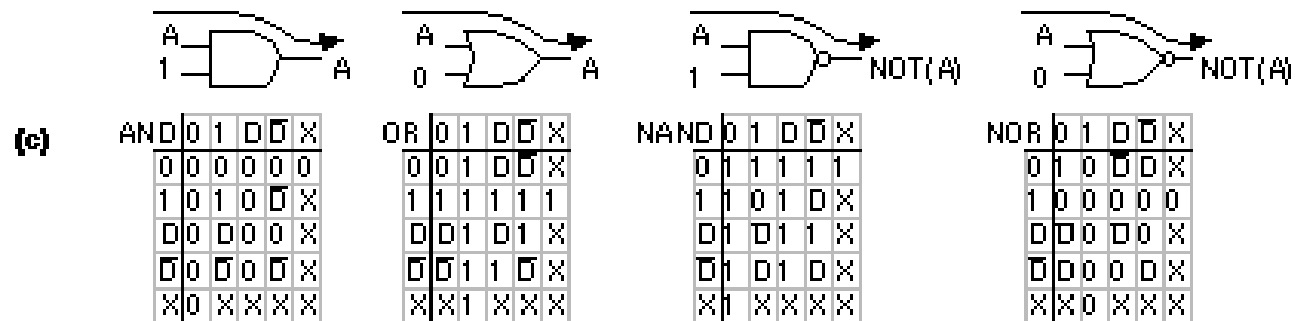
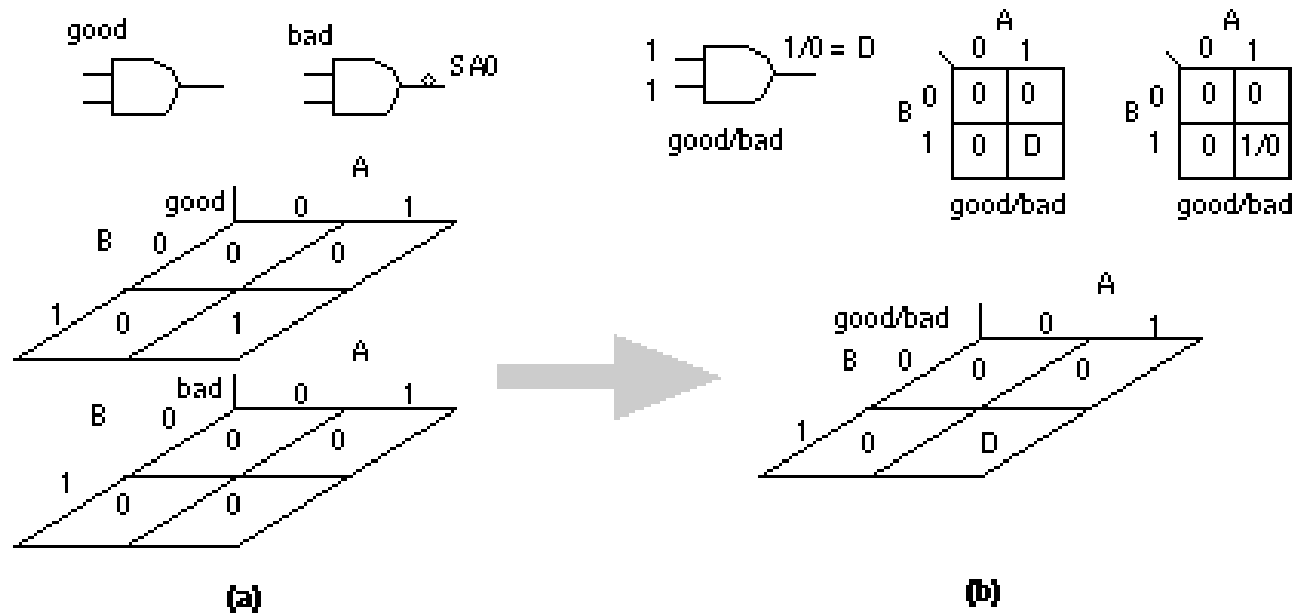


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CONTROLLABILITY AND OBSERVABILITY FOR FAULT DETECTION

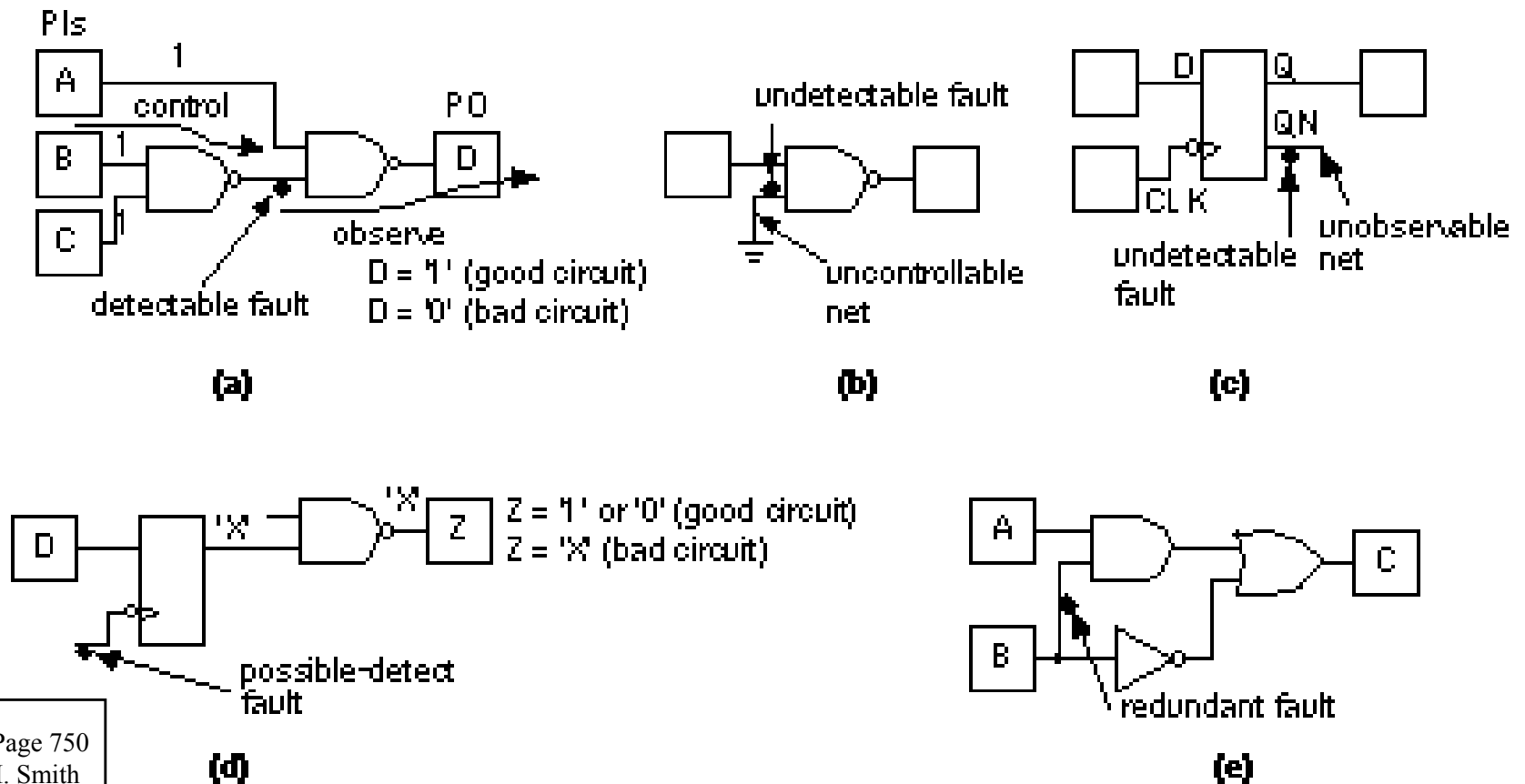


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MULTIPLEXED FLIP-FLOPS ARE USED FOR INTERNAL SCAN TESTING

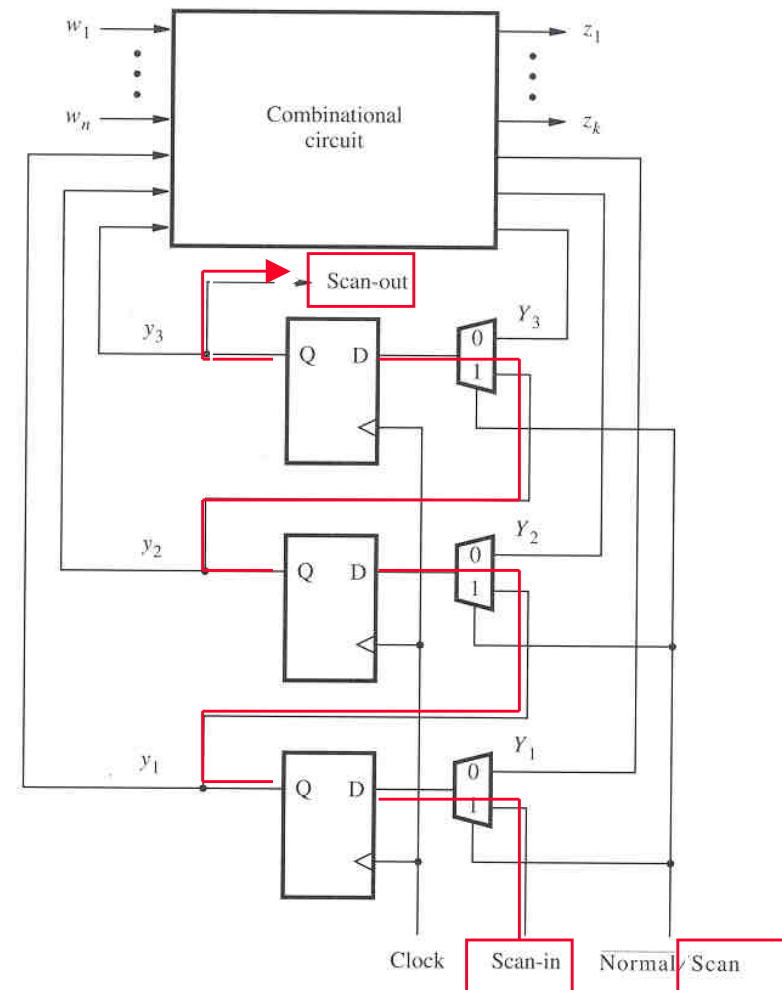
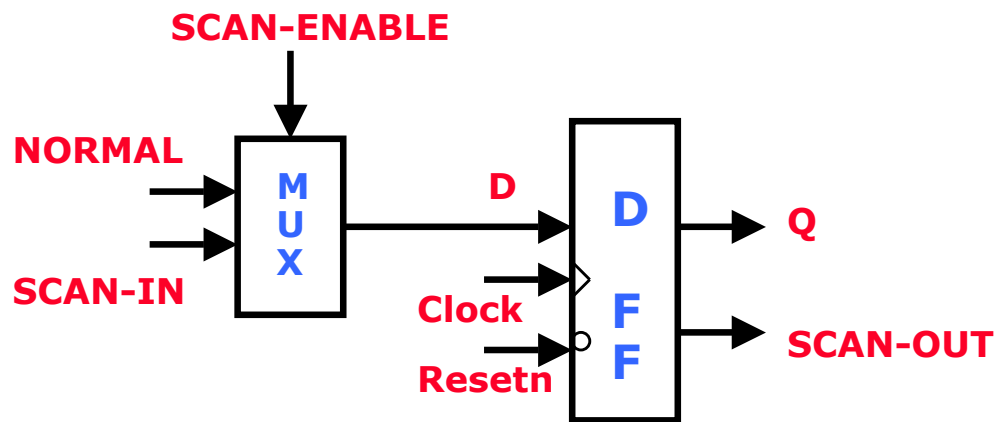
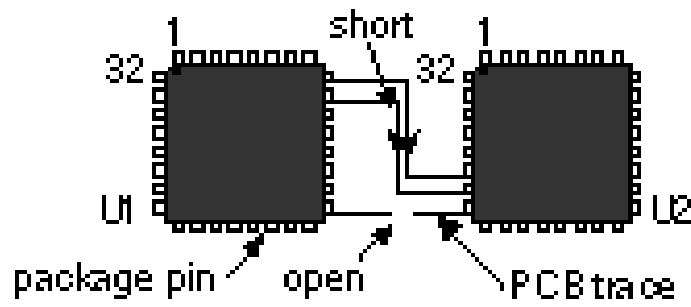
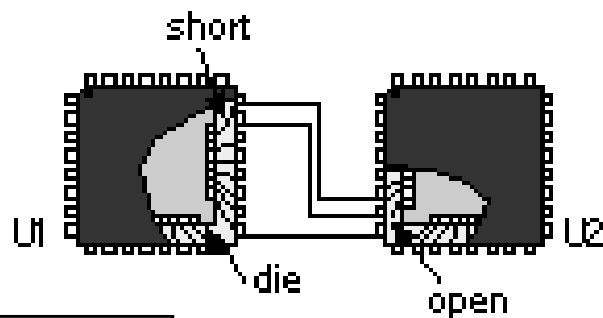


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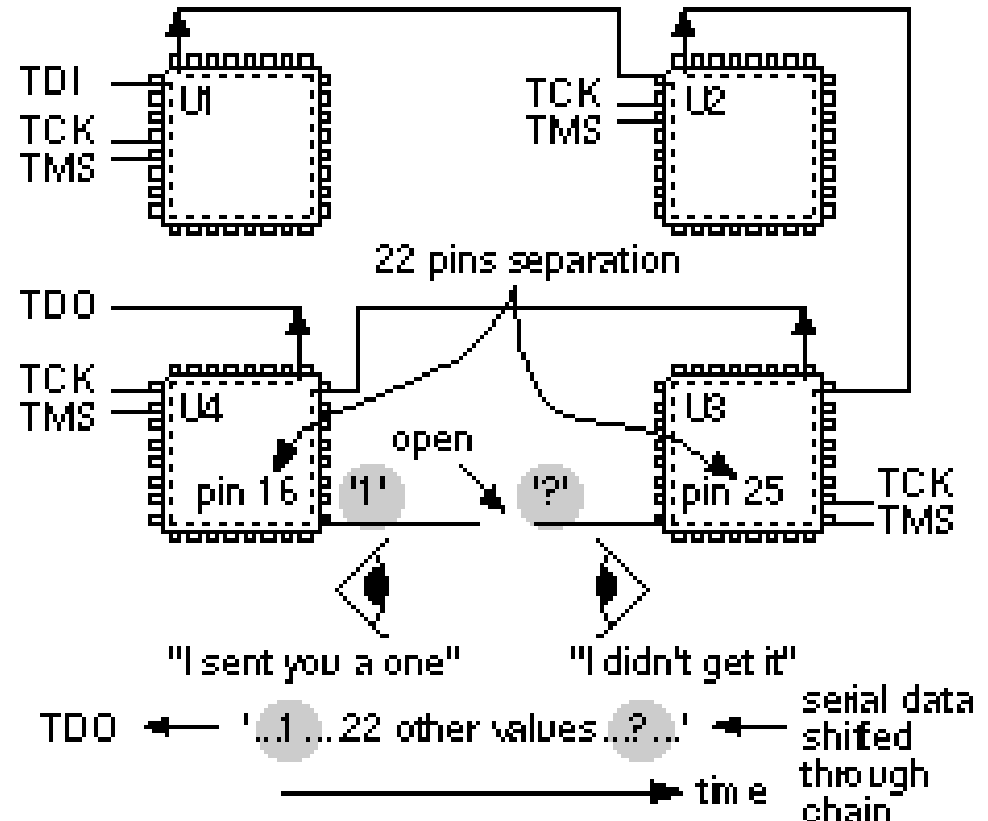
BOUNDARY SCAN CAN DETECT BOARD FAULTS AND PIN-POINT DEFECTIVE ICs



(a)



(b)



(c)

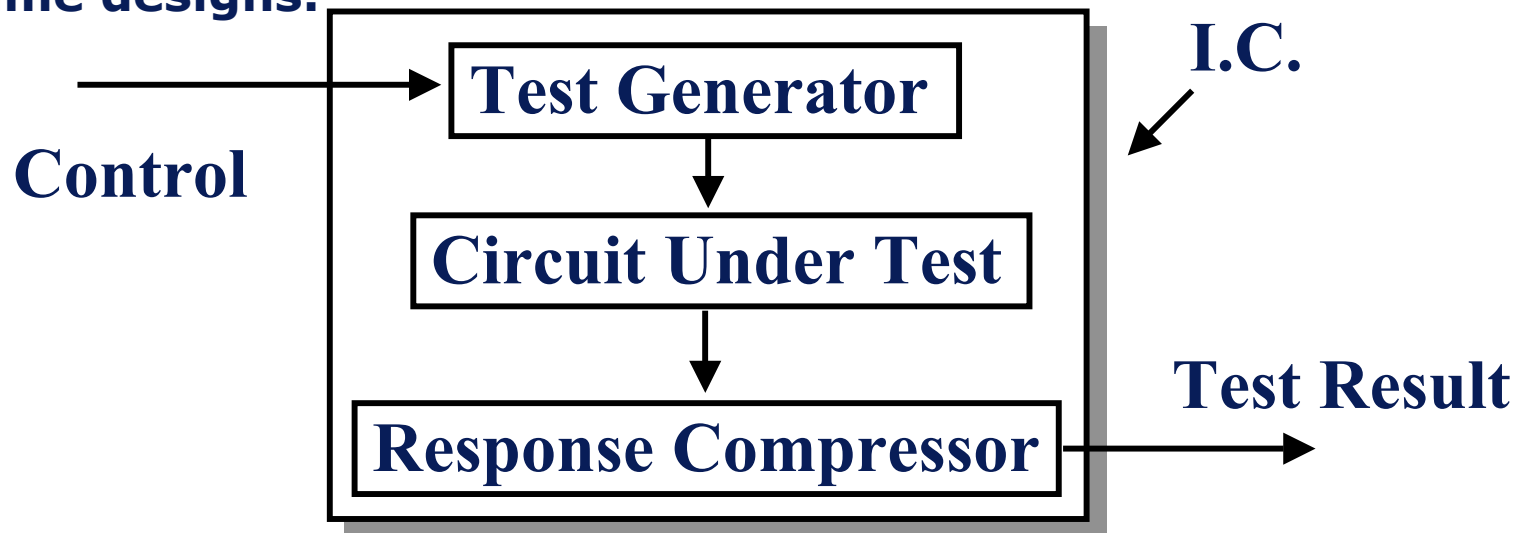
Fig. 14.1, Page 715
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ADVANTAGES OF BOUNDARY SCAN TESTING

- **Provides a standard protocol for invoking BIST in I.C.s after assembly onto P.C. boards.**
- **Allows I.C.s to be tested thoroughly in their complete, interconnected environment at any time during the life of the system.**
- **Provides standardized basis for thorough testing of all interconnect including system backplanes.**
- **Needs less expensive test equipment.**
- **Simplifies system-level diagnostic software.**

ADVANTAGES OF BUILT-IN SELF-TEST

- Eliminates the need to generate and apply a large set of test vectors externally via the I/O pins.
- Permits testing at speed under real-world conditions.
- Improves access to internal nodes.
- Assures that test issues are addressed early in the development cycle which results in higher quality, first-time designs.



SINGLE-INPUT SIGNATURE COMPRESSOR

A Linear Feedback Shift Register (LFSR) can compress a serial input into a residual signature.

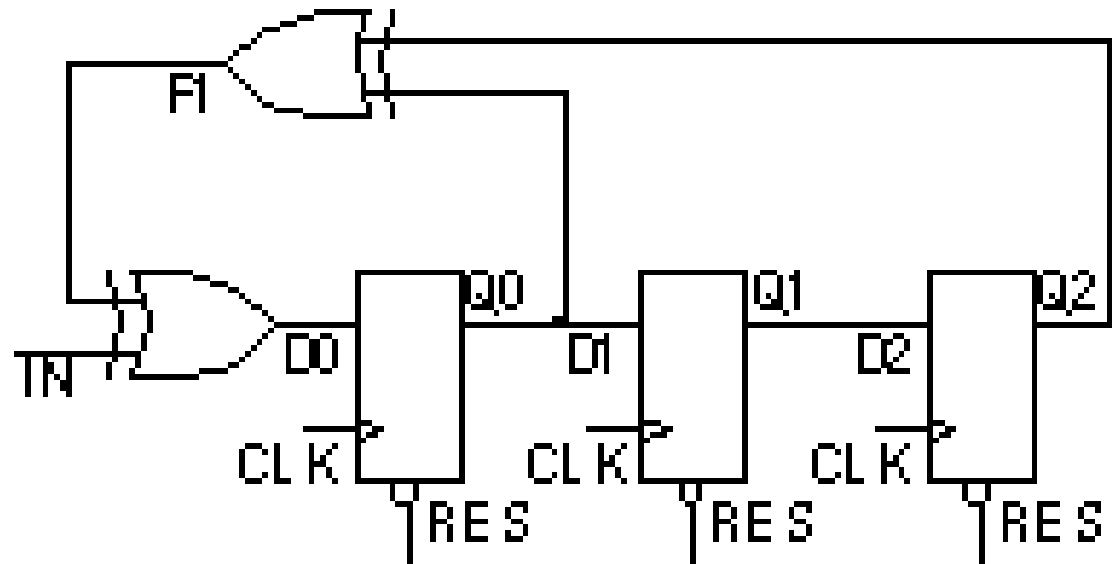


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BUILT-IN SELF-TEST (BIST)

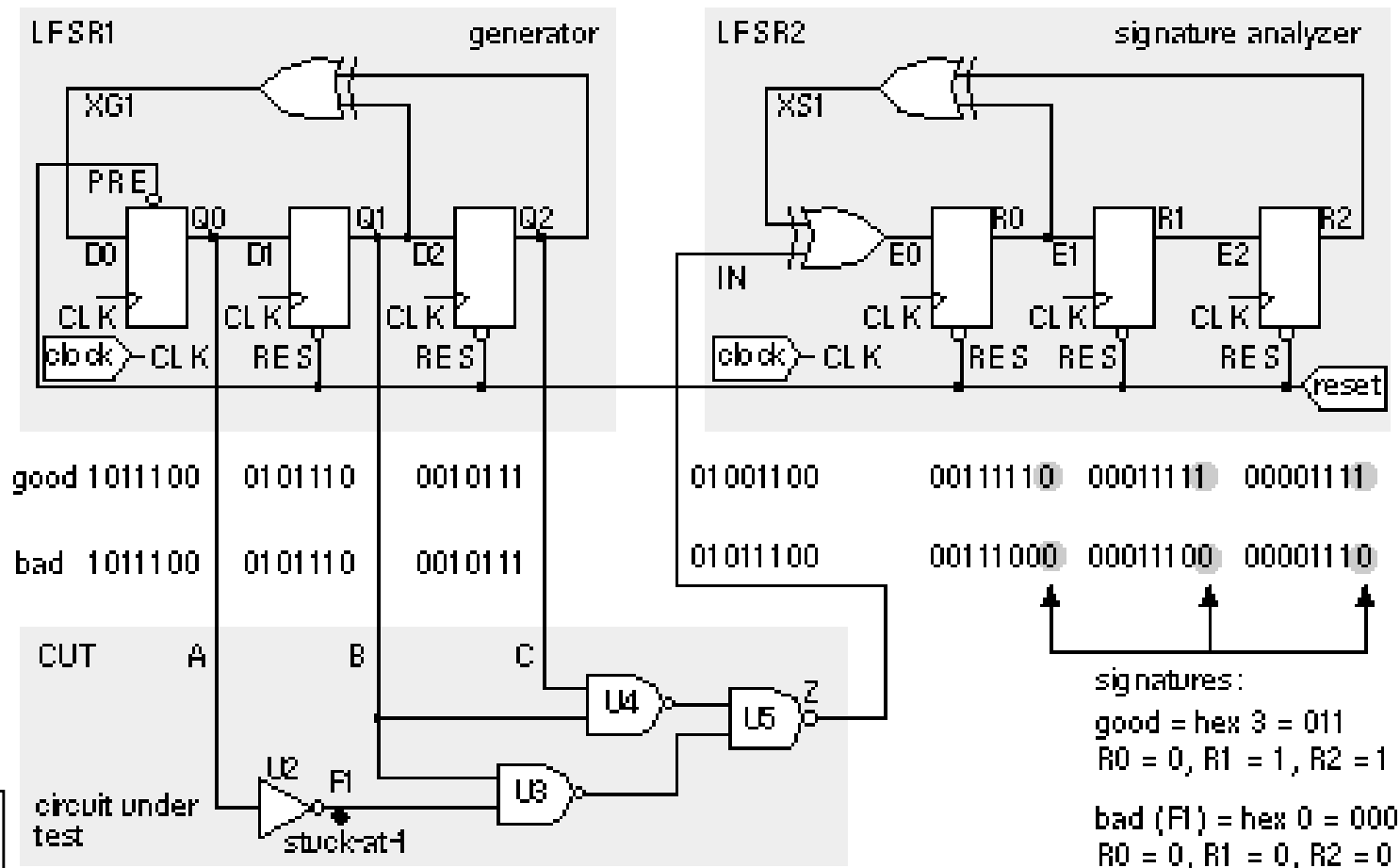
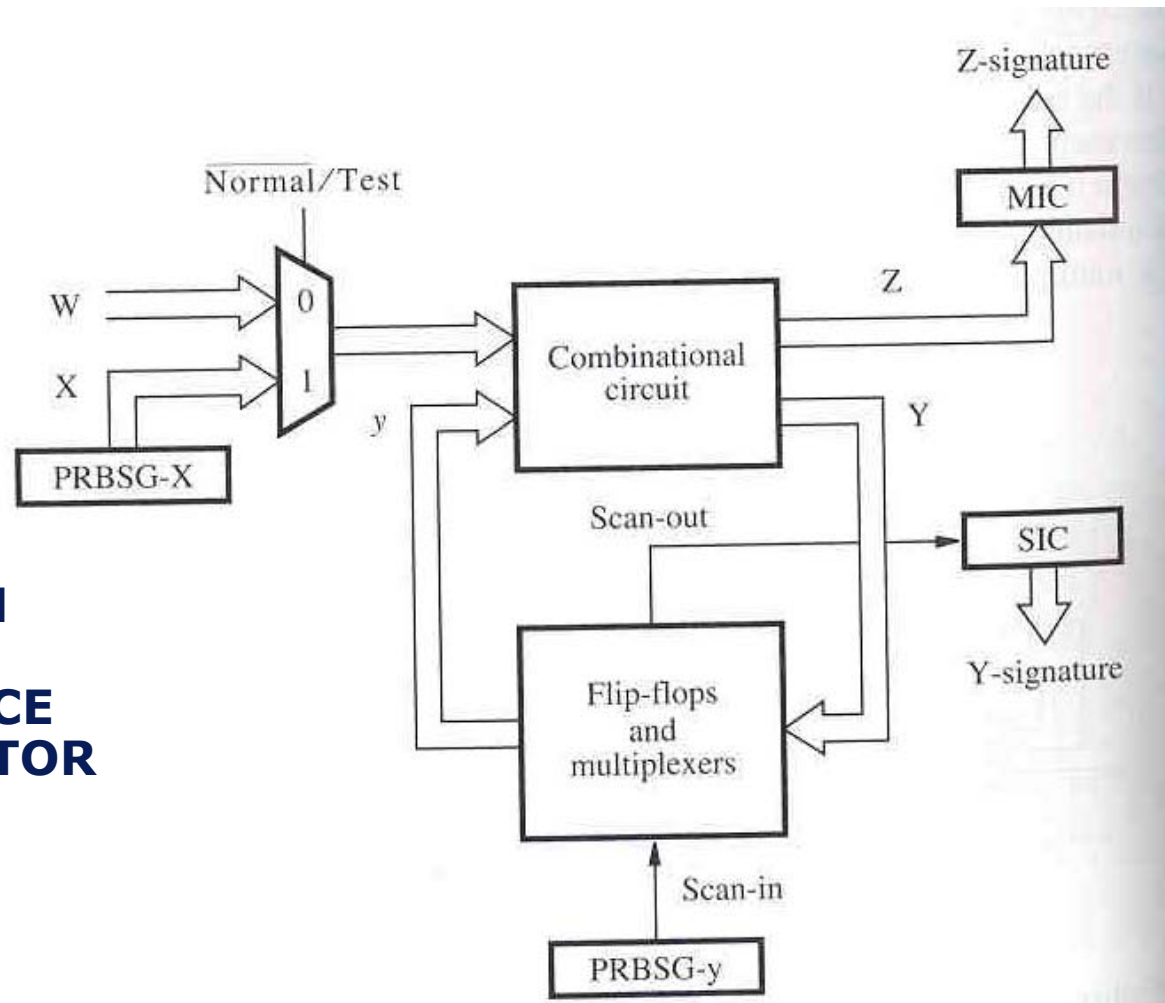


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BUILT-IN SELF-TEST (BIST)

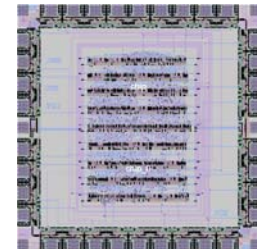
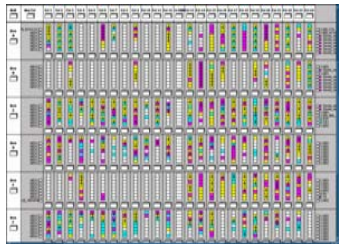
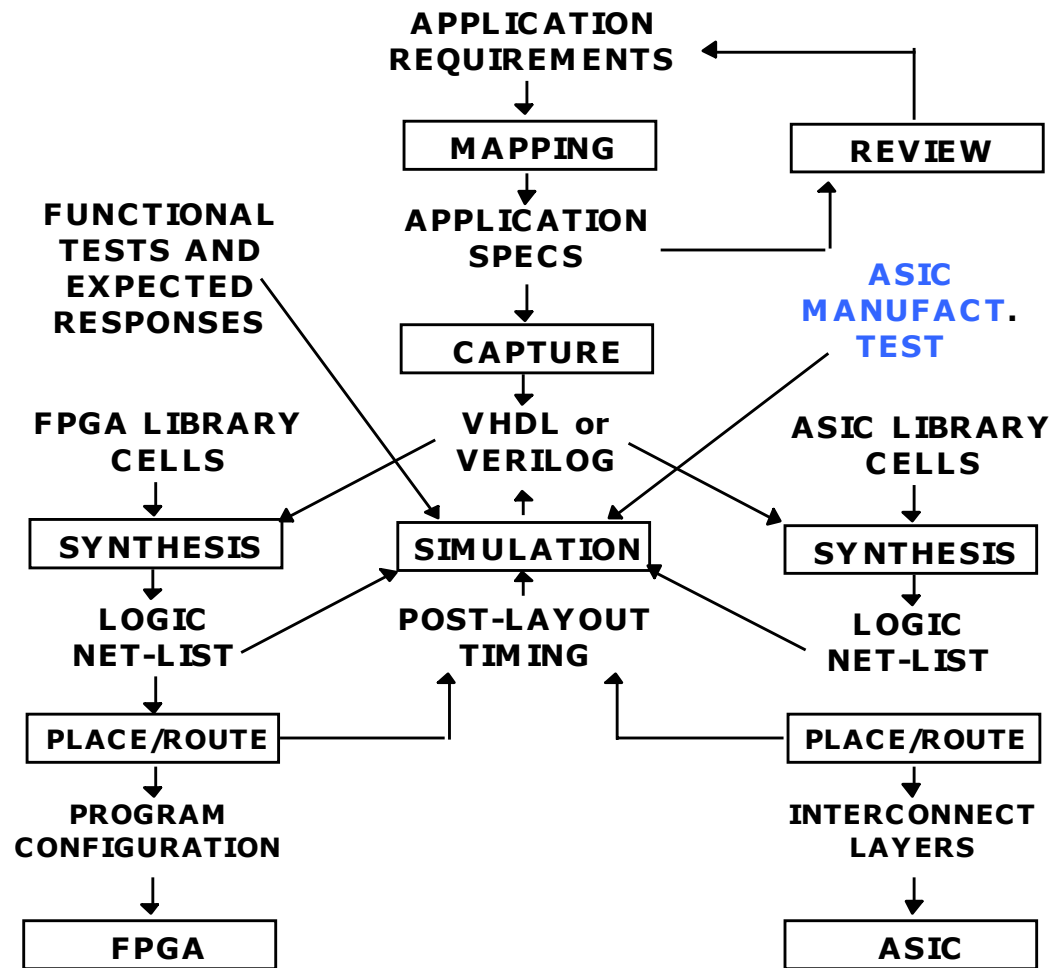
**PSEUDO
RANDOM
BINARY
SEQUENCE
GENERATOR**



**MULTIPLE
INPUT
COMPRESSOR**

**SINGLE
INPUT
COMPRESSOR**

DESIGN FLOW FOR FPGAS AND ASICS



COMPARISON OF PRODUCT DEVELOPMENT

<u>Design Stage</u>	<u>FPGA (weeks)</u>	<u>ASIC (weeks)</u>
• Design Specification	1.0	1.0
• Design Entry	1.6	1.6
• Functional Simulation	2.4	4.0
• Test Vector Generation	0.0	6.4
• Vendor Interface	0.0	1.6
• Prototype Test	1.6	1.6
• Prototype Lead Time	0.0	2.0
• Production Lead Time	0.0	6.0
• Total Design Cycle	7.0	24.0

COMPARISON OF PRODUCT COSTS

<u>EXPENSE</u>	<u>FPGA</u>	<u>ASIC</u>
• Raw unprogrammed part	8.00	4.00
• Design/Simulation	3.15	7.92
• Mfgr. Test Vectors	0	2.88
• Place/Route/Masks	0	2.20
• Final part	11.15	17.00

Costs in \$/part assuming quantity < 200,000 copies

HDL DESIGNS CAN BE TARGETED TO MULTIPLE LAYOUTS

